



# ro300fc.

FULL CONVECTION REFLOW OVEN

## RO300FC N2

**RO-CONTROL** – PC software  
for simulation, control, measurement and  
documentation of perfect solder profiles

**Full convection heating**  
ideal for lead free soldering

**Small footprint** 2m x 0,7m  
at 300 mm **process width**



**Integrated microprocessor control** with LCD

**Equal heating rates**  
at **minimal Delta T**. As an option with N2

**High throughput** still at  
**very small dimensions**

SWISS MADE

## ***Appropriate for Prototyping and volume production***

*“Even low and small volumes of boards have to be soldered safe and reliable – with the same ongoing quality level. The RO300FC is setting the benchmark for small-batch production worldwide”*

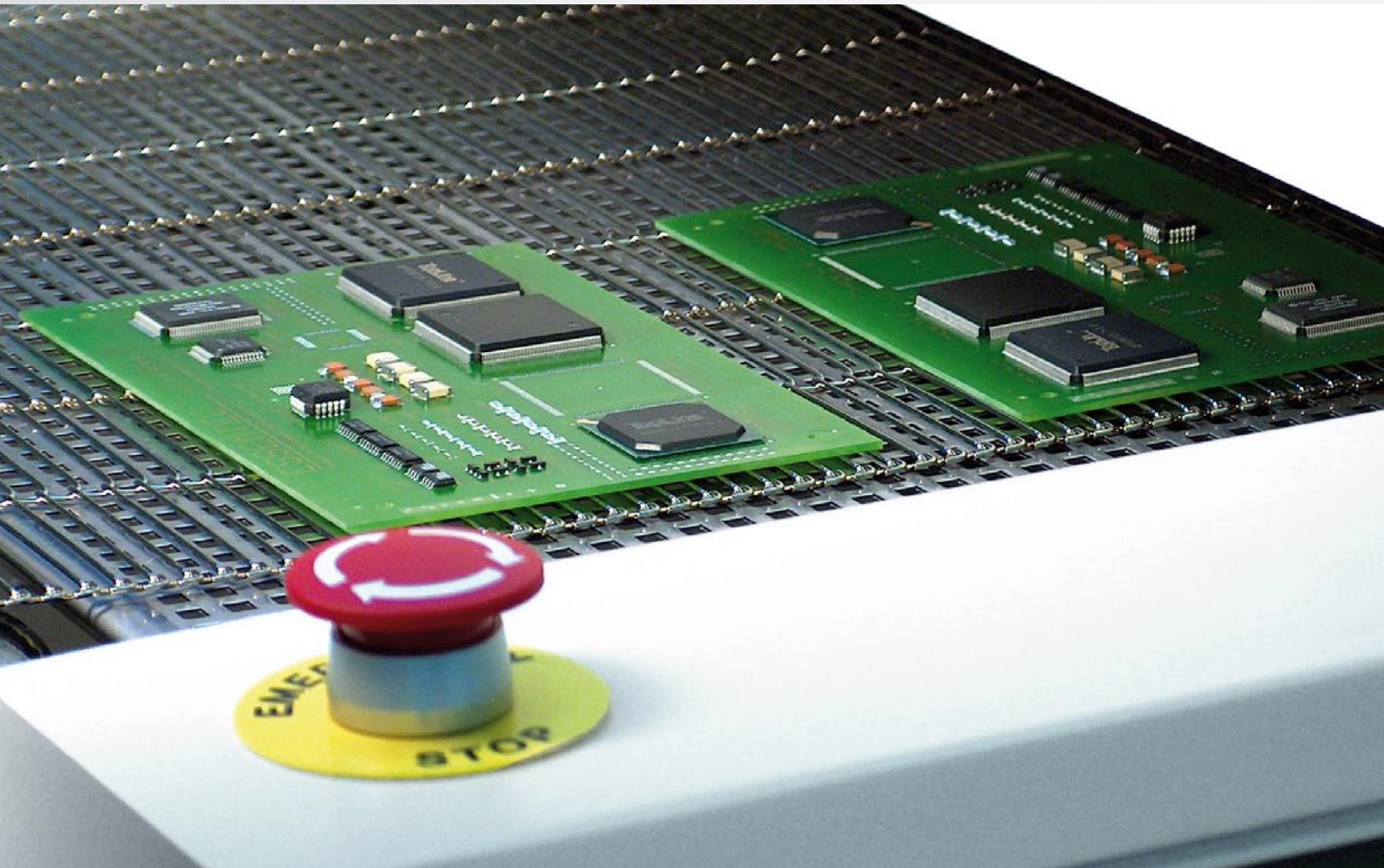
Soldering of complex SMD boards and new package technologies requires a well-controlled soldering process.

Lead free solders for SMT electronics have a higher melting temperature than solders with lead. The convection heating technology is the ideal solution for the reflow process. It guarantees the precise control of the higher process temperatures and the minimum thermal stress for the sensitive electronic components.

The integrated microprocessor control with LCD display provides an easy-to-use operator interface and storage capacity of up to 28 profiles. The memory provides program proposals and enough space for own profiles.



## OPERATION



### ***High tech engineering for a maximum in flexibility and quality***

The RO300FC exclusively heats with hot air convection and can be used for the different tasks in SMT assembly, especially for the reflow soldering of lead free solder pastes or the curing of adhesives. It features easy operation,

perfect reflow results and a robust construction. It is well suited for continuous production, small batch manufacturing and prototyping. Perfect zone separation allows the setup of profiles for all applications.

The vertical hot air stream evenly heats the complete PCB. The high air volume guarantees equal heating rates in all the components and the substrate. This technology eliminates the risk of hot spots or heat shadows.



## *Perfect soldering results*

### **Uniform heating**

The convection technology applies the same temperature everywhere on the board independent of component size or color, making programming as easy as possible.

### **RO-CONTROL**

New soldering tasks can be simulated and it offers unlimited storage space for programs. Measured temperature profiles can be superimposed graphically.

### **With or without Nitrogen**

The RO300FC-N2 can be operated with nitrogen or with air. The changeover takes less than five minutes.

### **Transport choices**

Depending on the application a mesh belt or a chain conveyor system is used for substrate transport.

### **Easy integration**

SMEMA connectors provide the ability to link the oven with any other compatible equipment.

### **Process control**

With the optional flying thermocouples, temperatures can be recorded directly on the board and displayed on the machine's LCD display.

### **Easy to maintain**

For the cleaning of flux residues all necessary parts of the oven can be removed easily and cleaned outside the oven.



## CONTACT US

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